

N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

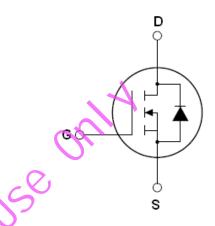
Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V _{DS}	650	V
R _{DS(ON)TYP}	220	mΩ
I_{D}	15	A



Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65T260D	TO-263	NCE65T260D
NCE65T260	TO-220	NCE65T260
NCE65T260F	TO-220F	NCE65T260F







TO-263

TO-220

TO-220F

Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	NCE65T260D NCE65T260	NCE65T260F	Unit
Drain-Source Voltage (V _{GS} =0V)	V _{DS}	650		V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	V _G S	±	30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	15	15*	Α
Continuous Drain Current at Tc=100°C	I _{D (DC)}	10	10*	Α
Pulsed drain current (Note 1)	I _{DM (pluse)}	60	60*	Α
Maximum Power Dissipation(Tc=25℃)	P _D	131	33.2	W
Derate above 25°C		1.05	0.265	w/°C
Single pulse avalanche energy (Note 2)	Eas	304		mJ
Avalanche current ^(Note 1)	I _{AR}	3		Α
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	1.6		mJ



Parameter	Symbol	NCE65T260D NCE65T260	NCE65T260F	Unit
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50		V/ns
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V}, I_{SD} \le I_D$	dv/dt	1	5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55	+150	°C

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	NCE65T260D NCE65T260	NCE65T260F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.95	3.76	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	80	°C /W

Table 3. Electrical Characteristics (TA=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
On/off states							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V	
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μA	
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA	
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =250μA	3	3.5	4	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =8A		220	260	mΩ	
Dynamic Characteristics	×\						
Input Capacitance	C _{iss}	\/ 50\/\/ 0\/		1210	1400	pF	
Output Capacitance	Coss	V_{DS} =50V, V_{GS} =0V,		74		pF	
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz		0.2		pF	
Total Gate Charge	Qg	\/ 400\/ L 45A		24.7	42	nC	
Gate-Source Charge	Q_{gs}	V _{DS} =480V,I _D =15A,		8.2		nC	
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		8.5		nC	
Switching times							
Turn-on Delay Time	t _{d(on)}			14		nS	
Turn-on Rise Time	t _r	V_{DD} =380V, I_{D} =8A,		8		nS	
Turn-Off Delay Time	$t_{d(off)}$	R_G =2.3 Ω , V_{GS} =10 V		55		nS	
Turn-Off Fall Time	t _f			7		nS	
Source- Drain Diode Characteristics							
Source-drain current(Body Diode)	I _{SD}	T -25°C			15	Α	
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			60	Α	
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =15A,V _{GS} =0V		0.9	1.2	V	
Reverse Recovery Time	t _{rr}			240		nS	
Reverse Recovery Charge	Q _{rr}	Tj=25°C,I _F =7.5A,di/dt=100A/μs		2		uC	
Peak Reverse Recovery Current	I _{rrm}			17		Α	

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

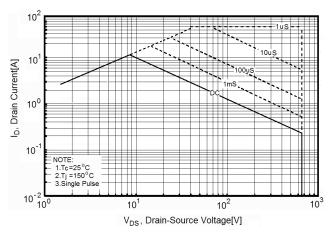


Figure 3. Source-Drain Diode Forward Voltage

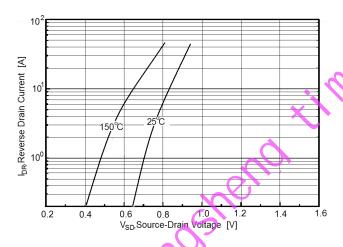


Figure 5. Transfer characteristics

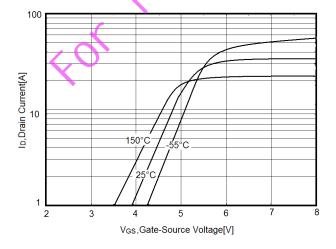


Figure 2. Safe operating area for TO-220F

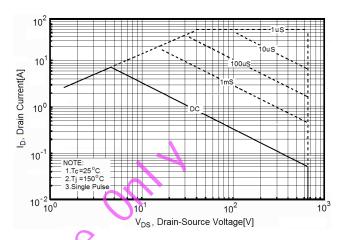


Figure4. Output characteristics

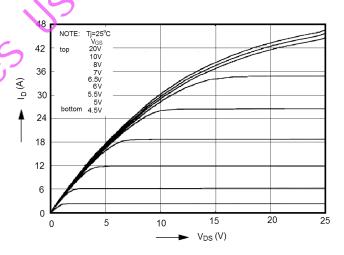


Figure 6. Static drain-source on resistance

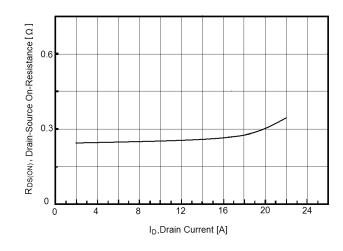




Figure 7. R_{DS(ON)} vs Junction Temperature

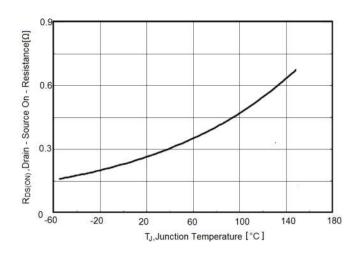


Figure8. BV_{DSS} vs Junction Temperature

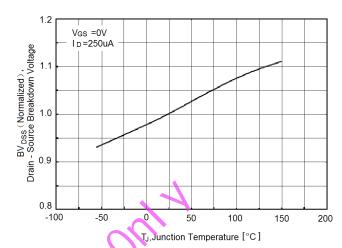
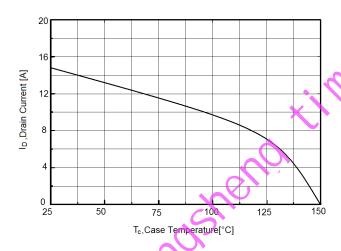


Figure 9. Maximum ID vs Junction Temperature



Elgure10. Gate charge waveforms

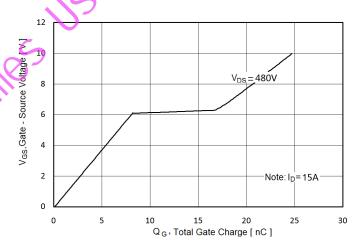


Figure11. Capacitance



Figure 12. Transient Thermal Impedance

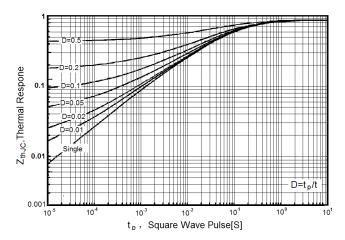
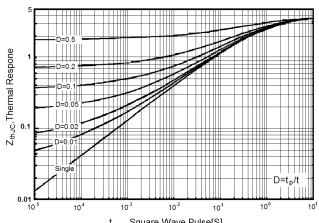




Figure 13. Transient Thermal Impedance for TO-220F

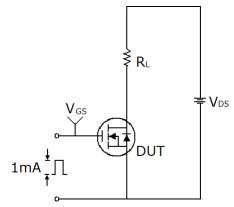


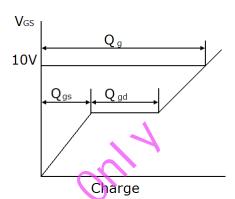
For Tondshend times Use Only



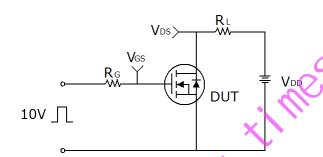
Test circuit

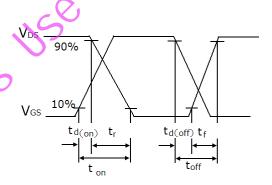
1) Gate charge test circuit & Waveform



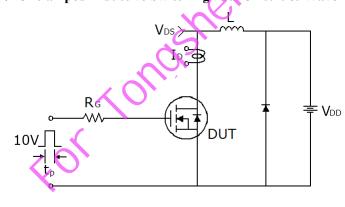


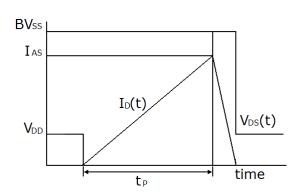
2) Switch Time Test Circuit:





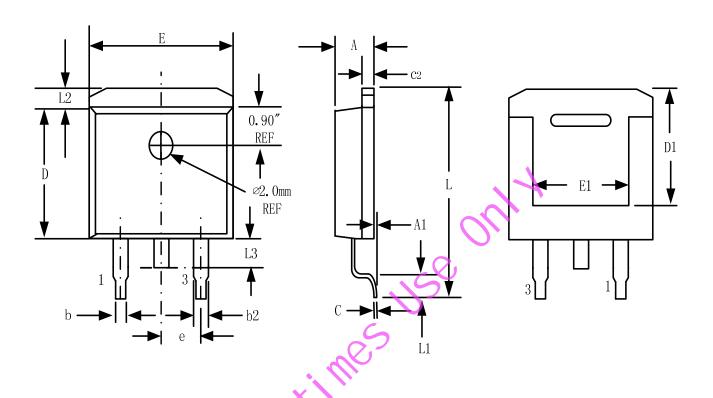
3) Unclamped Inductive Switching Test Circuit & Waveforms







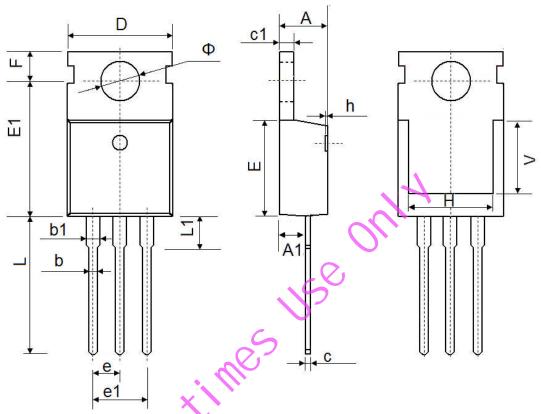
TO-263-3L Package Information



Symbol	Dimensions	Dimensions In Millimeters		s In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.32	4.57	0.170	0.180
A1	₹ <u>7</u> -	0.25		0.010
b	0.71	0.94	0.028	0.037
b2	1.15	1.40	0.045	0.055
С	0.46	0.61	0.018	0.024
c2	1.22	1.40	0.048	0.055
D	8.89	9.40	0.350	0.370
D1	8.01	8.23	0.315	0.324
Е	10.04	10.28	0.395	0.405
E1	7.88	8.08	0.310	0.318
е	2.54	BSC	0.100	BSC
L	14.73	15.75	0.580	0.620
L1	2.29	2.79	0.090	0.110
L2	1.15	1.39	0.045	0.055
L3	1.27	1.77	0.050	0.070



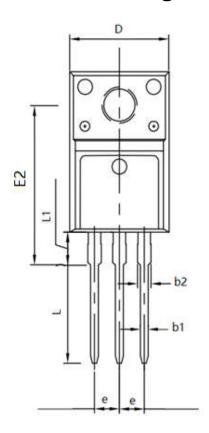
TO-220-3L-C Package Information

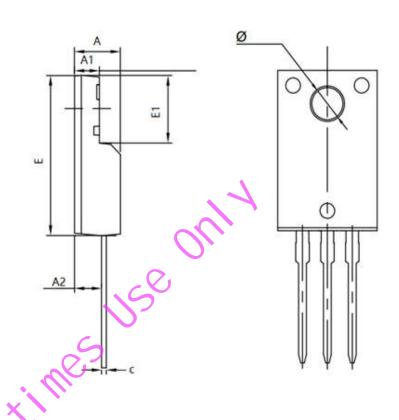


Compleal	Dimensions I	n Millimeters	Dimensions	s In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540	TYP.	0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500	REF.	0.295	REF.
Ф	3.400	3.800	0.134	0.150



TO-220F Package Information





Symbol	Dimensions in Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	4.500	4.900	0.177	0.193	
A1	2.340	2.740	0.092	0.108	
A2	2,560	2.960	0.101	0.117	
b1	0.700	0.900	0.028	0.035	
b2	1.180	1.580	0.046	0.062	
С	0.400	0.600	0.016	0.024	
D	9.960	10.360	0.392	0.408	
Ę.	15.670	15.970	0.617	0.629	
E1	6.500	6.900	0.256	0.272	
E2	15.500	16.100	0.610	0.634	
е	2.540 TYP		0.100) TYP	
Ф	3.080	3.280	0.121	0.129	
L	12.640	13.240	0.498	0.521	
L1	3.030	3.430	0.119	0.135	



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